



50V N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV _{DSS}	R _{DS(ON)} Max	I _D T _A = +25°C
	2Ω @V _{GS} = 5V	480mA
50V	2.5Ω @V _{GS} = 2.5V	440mA
	4Ω @V _{GS} = 1.8V	370mA

Description and Applications

This MOSFET is designed to minimize the on-state resistance (RDS(ON)) yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- Battery management systems
- Power management functions
- Load switches

Features and Benefits

- **Dual N-Channel MOSFET**
- Low On-Resistance
- Very Low Gate Threshold Voltage, 1.0V Max
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Ultra-Small Surface Mount Package
- **ESD Protected**
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/104/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please contact us or your local Diodes representative.

https://www.diodes.com/quality/product-definitions/

Mechanical Data

- Package: SOT563
- Package Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.006 grams (Approximate)





Top View

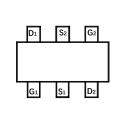
SOT563



Bottom View



Gate Protection Gate Protection **S1** Diode Equivalent Circuit



Top View

S₂

Ordering Information (Note 4)

Part Number	Backago	Packing			
Fait Number	Package	Qty.	Carrier		
DMN52D0UVA-7	SOT563	3,000	Reel		
DMN52D0UVA-13	SOT563	10,000	Reel		

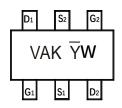
Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

DMN52D0UVA Document number: DS44807 Rev. 3 - 2



Marking Information



 $\underline{\underline{V}}$ AK = Product Type Marking Code $\underline{\underline{Y}}$ W = Date Code Marking \overline{Y} = Year (ex: 2 = 2022)

W = Week (ex: a = week 27; z represents week 52 and 53)

Date Code Key

Year	2022	2023	2024	2025	2026	2027	2028	2029	2030	2031	2032	2033
Code	2	3	4	5	6	7	8	9	0	1	2	3
Week	Week 1-26			27-52				53				
Code	A-Z				а	-Z				Z		

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit	
Drain-Source Voltage		VDSS	50	V	
Gate-Source Voltage		Vgss	±12	V	
Continuous Drain Current (Note 6) V _{GS} = 5V Steady $T_A = +25$ °C $T_A = +70$ °C			lo	480 380	mA
Maximum Continuous Body Diode Forward Curr	ent (Note 6)	Is	480	mA	
Pulsed Drain Current (10µs Pulse, Duty Cycle =	1%)	I _{DM}	1.2	А	
Pulsed Source Current (10µs Pulse, Duty Cycle	= 1%)	Ism	1.2	Α	

Thermal Characteristics

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)		P_D	0.48	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	Reja	261	°C/W
Total Power Dissipation (Note 6)		P _D	0.89	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	R _{0JA}	139	°C/W
Operating and Storage Temperature Range		TJ, TSTG	-55 to +150	°C

Notes:

5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.6. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate.



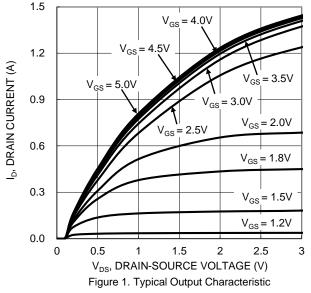
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BVDSS	50	_	_	V	$V_{GS} = 0V, I_{D} = 250\mu A$	
Zero Gate Voltage Drain Current	IDSS	l	_	1	μΑ	V _{DS} = 50V, V _{GS} = 0V	
Gate-Source Leakage	I _{GSS}		_	±10	μΑ	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	V _{GS(TH)}	0.49	_	1.0	V	$V_{DS} = V_{GS}$, $I_D = 250\mu A$	
		1	1.6	4.0		V _G S = 1.8V, I _D = 50mA	
Static Drain-Source On-Resistance	RDS(ON)	1	1.2	2.5	Ω	$V_{GS} = 2.5V, I_D = 50mA$	
		_	1.0	2.0		$V_{GS} = 5.0V, I_{D} = 50mA$	
Diode Forward Voltage	VsD	-	0.6	1.2	V	V _G S = 0V, I _D = 50mA	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	Ciss	-	39	_	pF		
Output Capacitance	Coss	1	4.8	_	pF	V _{DS} = 25V, V _{GS} = 0V, -f = 1.0MHz	
Reverse Transfer Capacitance	Crss	1	3.6	_	pF	1 - 1.00012	
Gate Resistance	Rg	1	47.8	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge (VGS = 4.5V)	Qg	_	0.8	_	nC		
Total Gate Charge (V _{GS} = 10V)	Qg	_	1.5	_	nC	\/ 25\/ - 50m/	
Gate-Source Charge	Qgs	_	0.1	_	nC	$V_{DS} = 25V, I_D = 50mA$	
Gate-Drain Charge	Q_{gd}	1	0.1	_	nC		
Turn-On Delay Time	td(on)		1.05	_	ns		
Turn-On Rise Time	t _R	1	11.3	_	ns	$V_{DS} = 25V, V_{GS} = 10V,$	
Turn-Off Delay Time	tD(OFF)		33	_	ns	$R_G = 50\Omega$, $I_D = 50mA$	
Turn-Off Fall Time	tF	_	38.5	_	ns		

Notes:

^{7.} Short duration pulse test used to minimize self-heating effect. 8. Guaranteed by design. Not subject to product testing.





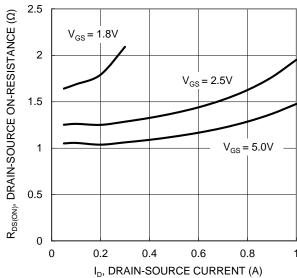


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

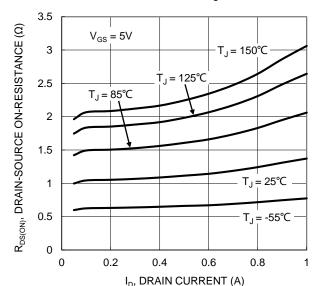


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature

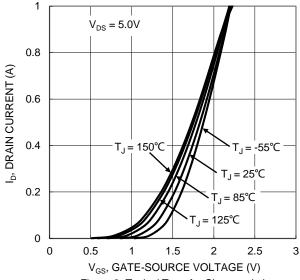


Figure 2. Typical Transfer Characteristic

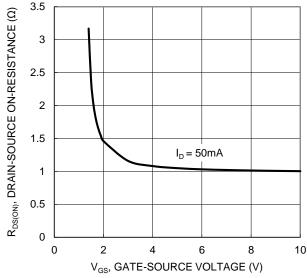


Figure 4. Typical Transfer Characteristic

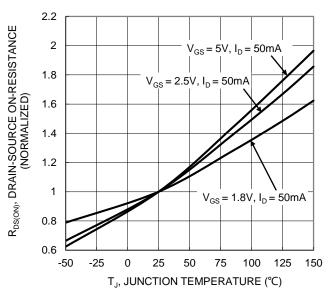


Figure 6. On-Resistance Variation with Junction Temperature



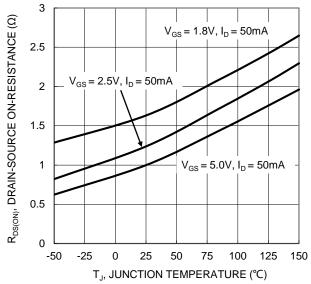


Figure 7. On-Resistance Variation with Junction Temperature

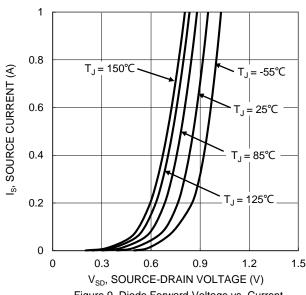


Figure 9. Diode Forward Voltage vs. Current

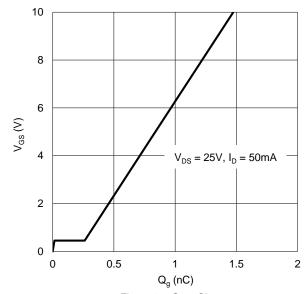


Figure 11. Gate Charge

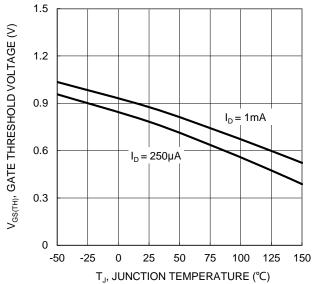
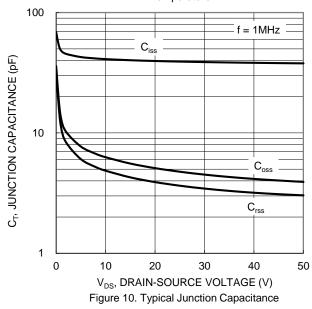


Figure 8. Gate Threshold Variation vs. Junction Temperature



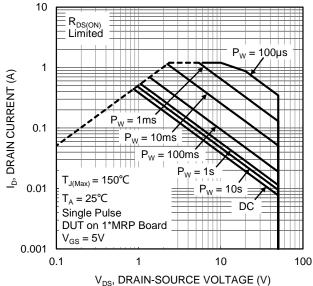


Figure 12. SOA, Safe Operation Area



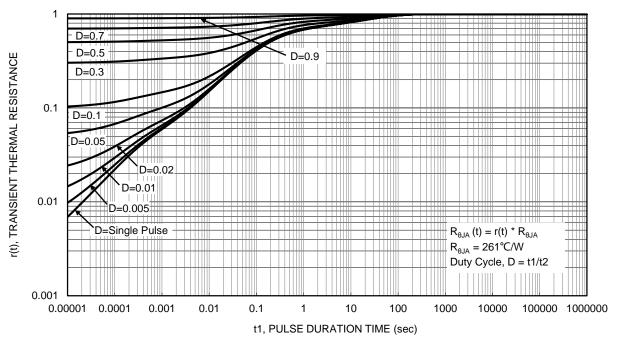


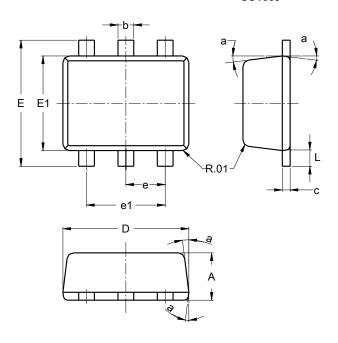
Figure 13. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT563

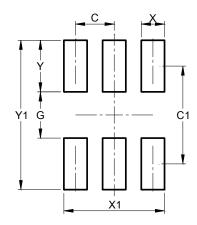


SOT563							
Dim	Min	Max	Тур				
Α	0.55	0.60					
b	0.15	0.30	0.20				
С	0.10	0.18	0.11				
D	1.50	1.70	1.60				
Е	1.55	1.70	1.60				
E1	1.10	1.25	1.20				
е			0.50				
e1	0.90	1.10	1.00				
L	0.10	0.30	0.20				
а	8°	9°	7°				
All Dimensions in mm							

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT563



Dimensions	Value (in mm)
С	0.500
C1	1.270
G	0.600
Х	0.300
X1	1.300
Y	0.670
Y1	1.940



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